

• General Description

The ZM095N03S combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- DC/DC Converters in Computing, Servers
- Isolated DC/DC Converters in Telecom and Industrial
- POL application
- BLDC Motor driver

• Ordering Information:

Part NO.	ZM095N03S
Marking	ZM095N03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	4000

• Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$)

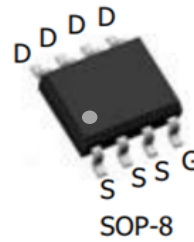
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^②	$I_D @ T_C = 25^\circ\text{C}$	10	A
	$I_D @ T_C = 75^\circ\text{C}$	7.6	A
	$I_D @ T_C = 100^\circ\text{C}$	6.3	A
Pulsed Drain Current ^①	I_{DM}	20	A
Total Power Dissipation ^②	$P_D @ T_C = 25^\circ\text{C}$	3.4	W
Total Power Dissipation	$P_D @ T_A = 25^\circ\text{C}$	0.69	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$
Single Pulse Avalanche Energy @ $L = 0.1\text{mH}$	E_{AS}	31	mJ
Avalanche Current @ $L = 0.1\text{mH}$	I_{AS}	25	A

• Product Summary


$V_{DS} = 30\text{V}$

$R_{DS(ON)} = 9.7\text{m}\Omega$

$I_D = 10\text{A}$



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case ^②	R _{thJC}	-	-	36	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	180	° C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V			±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A		9.7	12	mΩ
		V _{GS} =4.5V, I _D =6A		13	18	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =5A		9		s
Source-drain voltage	VSD	I _S =10A			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz	-	850	-	pF
Output capacitance	C _{oss}		-	190	-	
Reverse transfer capacitance	C _{rss}		-	100	-	

Gate Charge characteristics(T_a= 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DD} =25V	-	12	-	nC
Gate - Source charge	Q _{gs}	I _D = 8A	-	4	-	
Gate - Drain charge	Q _{gd}	V _{GS} = 10V	-	8	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

Fig.1 Gate-Charge Characteristics

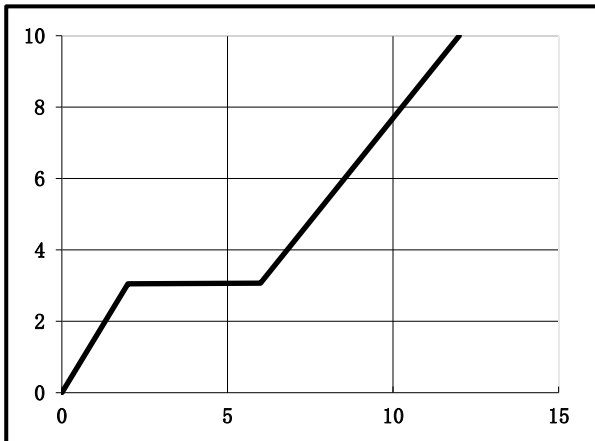


Fig.2 Capacitance Characteristics

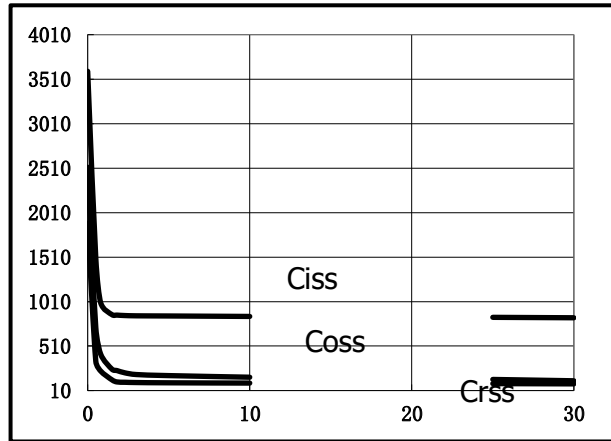


Fig.3 Power Dissipation Derating Curve

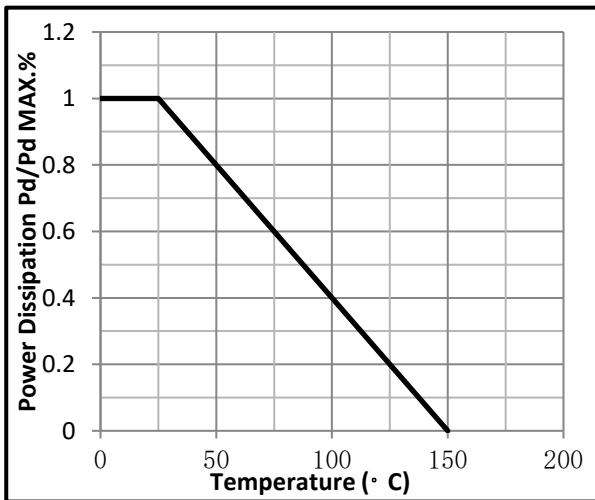


Fig.4 Typical output Characteristics

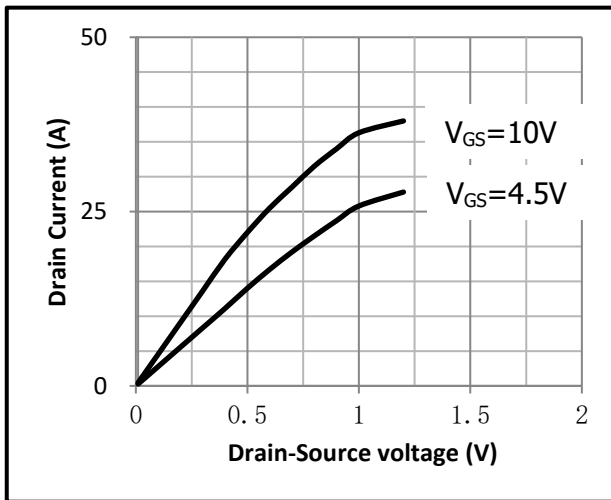


Fig.5 Threshold Voltage V.S Junction Temperature

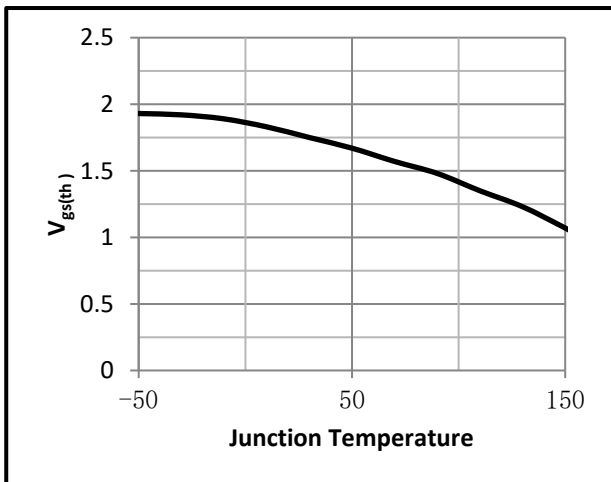


Fig.6 Resistance V.S Drain Current

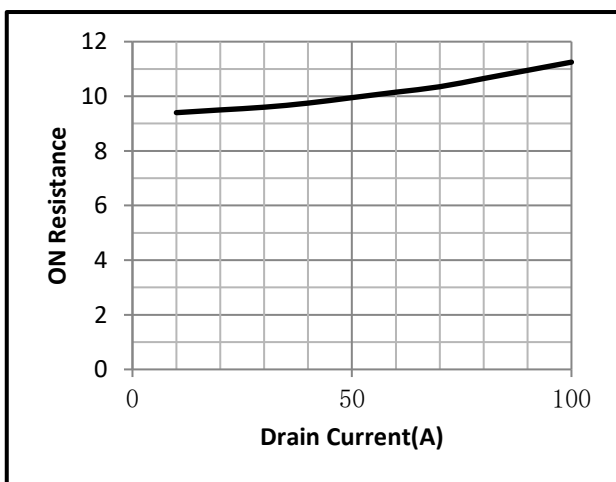


Fig.7 On-Resistance VS Gate Source Voltage

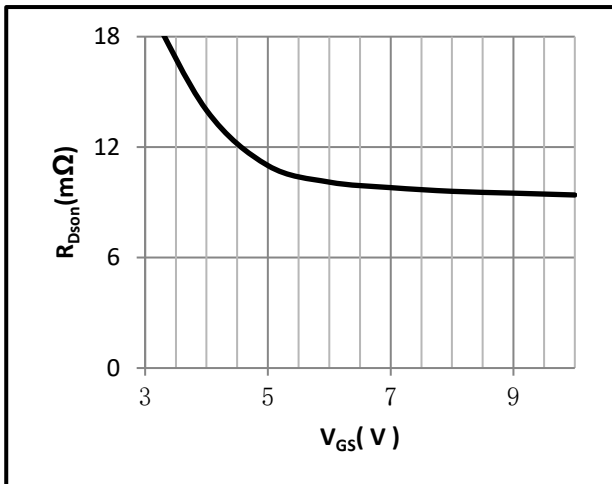


Fig.8 On-Resistance V.S Junction Temperature

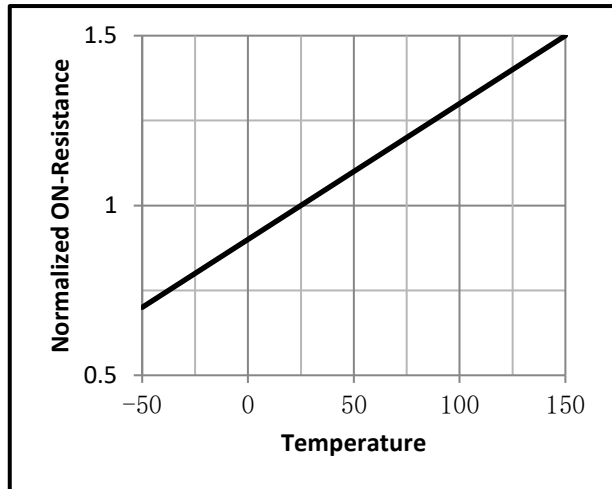


Fig.9 Switching Time Measurement Circuit

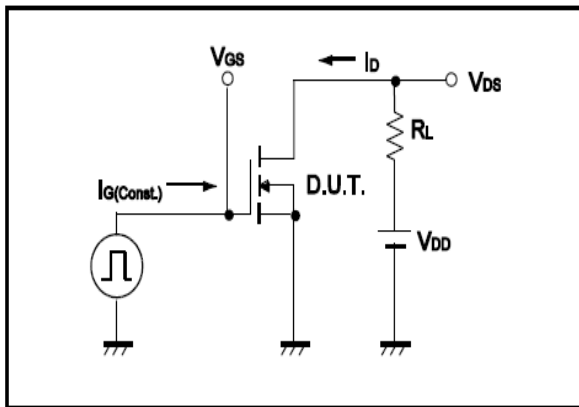


Fig.10 Gate Charge Waveform

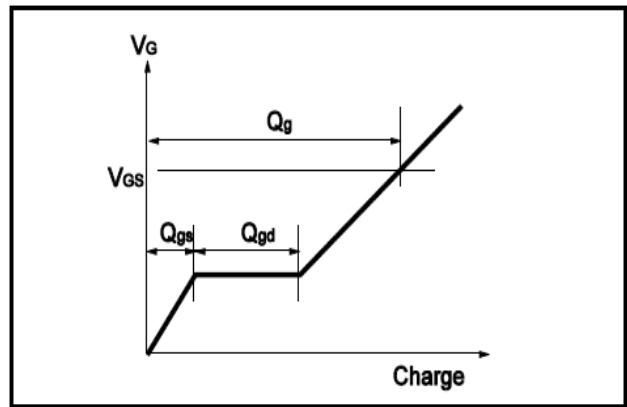


Fig.11 Switching Time Measurement Circuit

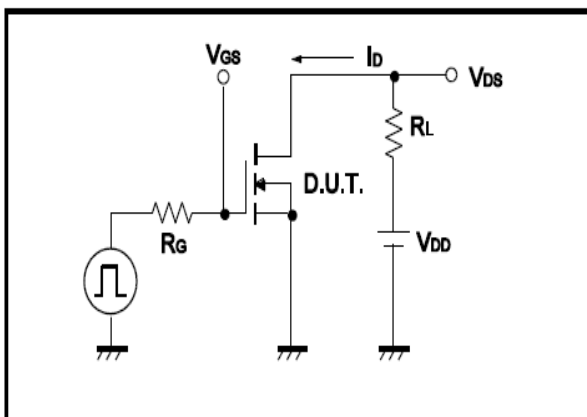
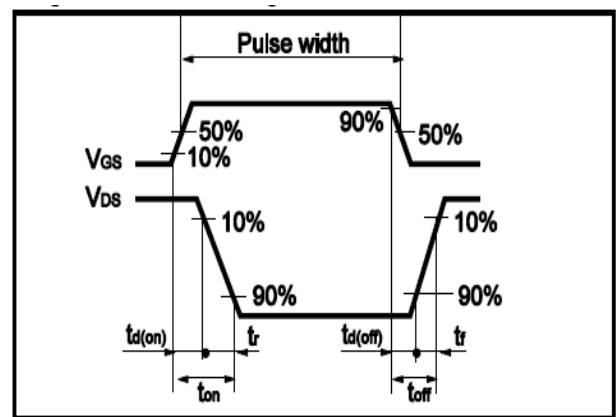


Fig.12 Gate Charge Waveform





●Dimensions(SOP8)

Unit: mm

SYMBOL	min	TYP	max	SYMBOL	min		max
A	4.80		5.25	C	1.30		1.75
A1	0.37		0.49	C1	0.55		0.75
A2		1.27		C2	0.55		0.65
A3		0.41		C3	0.05		0.20
B	5.80		6.20	C4	0.10	0.20	0.23
B1	3.80		4.10	D		1.05	
B2		5.00		D1	0.40		0.62

